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# FXLS8972CFR1:Part Detail

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## **General Information**

Part Number	FXLS8972CFR1
Description	3axis 2/4/8/16g 2X2 DFN10
Product Line	G8900AF
PTI	AKAL
Material Type	Tested Packaged Device
Life Cycle Description (code)	PRODUCT NEWLY INTRO D/RAMP-UP
Status	Active
Application/Qualification Tier	AUTO; >=10 YEARS APPLICATION LIFE

## **Package Information**

Package Type and Termination Count	DFN 10
Package Description and Mechanical Drawing	DFN 10 2*2*0.95 P0.4 IJ
Package Length (nominal)(mm)	2.000
Package Width (nominal)(mm)	2.000
Package Thickness (nominal)(mm)	0.950
Tape & Reel	Yes

## **Environmental and Compliance Information**

Pb-Free	Contact Us
RoHS Compliant	Contact Us
Material Composition Declaration (MCD)	Contact Us
RoHS Certificate of Analysis (CoA)	Contact Us
2nd Level Interconnect	Contact Us
Moisture Sensitivity Level (MSL)	3
Floor Life	168 HOURS
Peak Package Body Temperature (PPT)(°C)	260
Maximum Time at Peak Temperature (s)	40

Downloaded from Arrow.com.

Number of Reflow Cycles 3

REACH SVHC NXP REACH Statement

UL94 (plastics flammability test) V0;Burning stops within 10 seconds on a vertical specimen;no drips allowed

## **Manufacturing Information**

Micron Size(µm) 1

## **Ordering Information**

Minimum Package Quantity (MPQ)	3000
MPQ Container	REEL
Exempt from Minimum Delivery Value	Yes
Preferred Order Quantity (POQ)	3000
POQ Container	REEL
Export Control Classification Number (US)	EAR99
Harmonized Tariff (	
CCATS Document	
ENC Status	-
Other Trade Compliance Documents	
Budgetary Price excluding tax(US Currency	-

## **Operating Characteristics**

Sample Exception Availability N

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